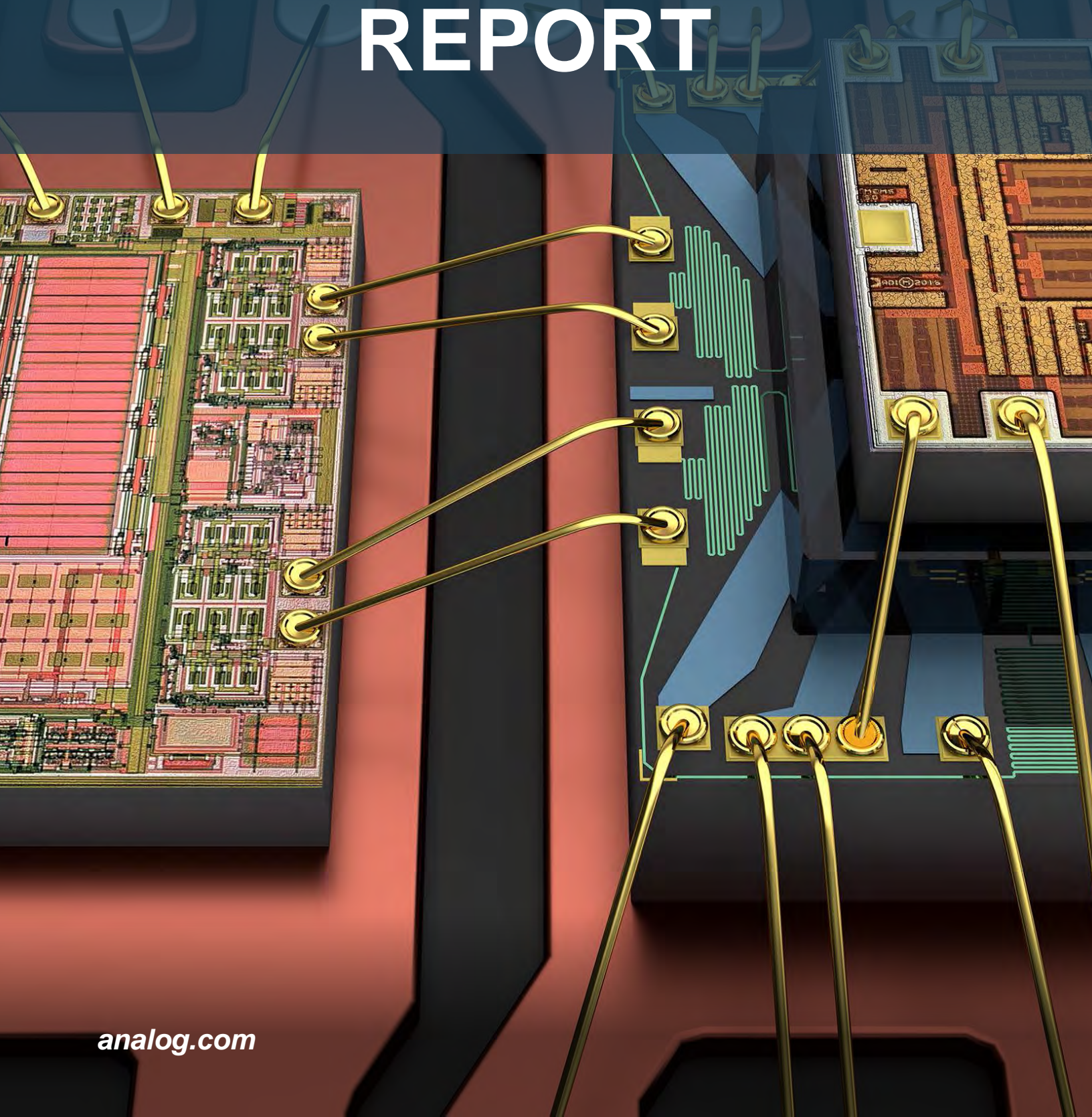


# RELIABILITY REPORT





NOW PART OF



## Reliability Data Report Product Family R531

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LT1965 / LT3007 / LT3008 / LT3009 /  
LT3015 / LT3022 / LT3029 / LT3030 /  
LT3042 / LT3045 / LT3048 / LT3050 /  
LT3055 / LT3060 / LT3061 / LT3062 /  
LT3063 / LT3065 / LT3066 / LT3080 /  
LT3081 / LT3082 / LT3083 / LT3085 /  
LT3086 / LT3088 / LT3089 /  
LT3090 / LT3091 / LT3092 /  
LT3094 / LT3095

# Reliability Data Report

## Report Number: R531

Report generated on: Wed Nov 06 11:39:32 PST 2019

<b>OPERATING LIFE TEST</b>					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C) <sup>1</sup>	No. of FAILURES <sub>2,3</sub>
SSOP/TSSOP	460	0941	1428	1159	0
TO-3	462	1034	1034	1244	0
SOIC/MSOP	1456	0813	1518	5672	0
QFN/DFN	2272	0713	1630	3772	0
SOT	308	0908	1421	1724	0
Totals	4,958	-	-	13,571	0
<b>HIGHLY ACCELERATED STRESS TEST AT +130 DEG C / 85% RH</b>					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+85°C) <sup>4</sup>	No. of FAILURES
SOT	1324	1332	1503	2557	0
Totals	1,324	-	-	2,557	0
<b>PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C</b>					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
DD PAK	9982	0811	1709	1546	0
QFN/DFN	21380	0552	1741	2628	0
SSOP/TSSOP	4700	0550	1704	539	0
SOIC/MSOP	12360	0739	1715	828	0
TO-220	5108	0813	1713	965	0
SOT	20748	0730	1712	1319	0
Totals	74,278	-	-	7,825	0
<b>TEMP CYCLE FROM -65 TO 150 DEG C</b>					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
DD PAK	9240	1045	1709	3352	0
QFN/DFN	19518	0552	1741	8398	0
SSOP/TSSOP	4160	0550	1704	1380	0
SOIC/MSOP	13324	0739	1715	3719	0
TO-220	4092	1045	1713	2050	0
SOT	13934	0740	1712	3203	0
Totals	64,268	-	-	22,102	0

(1) Assumes Activation Energy = 1.0 Electron Volts  
(2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =0.14 FITS  
(3) Mean Time Between Failure in Years = 845081.19  
(4) Assumes 20X Acceleration from 85 °C to +130 °C  
Note 1: 1 FIT = 1 Failure in One Billion Hours.  
Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL Preconditioning

# Reliability Data Report

## Report Number: R531

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<b>THERMAL SHOCK FROM -65 TO 150 DEG C</b>					
<b>PACKAGE TYPE</b>	<b>SAMPLE SIZE</b>	<b>OLDEST DATE CODE</b>	<b>NEWEST DATE CODE</b>	<b>K DEVICE CYCLES</b>	<b>No. of FAILURES</b>
DD PAK	7564	0811	1709	2527	0
QFN/DFN	19950	0552	1741	8393	0
SSOP/TSSOP	4248	0550	1704	1467	0
SOIC/MSOP	13142	0739	1715	3555	0
TO-220	2880	0813	1713	1146	0
SOT	14174	0740	1712	2944	0
Totals	61,958	-	-	20,032	0
<b>HIGH TEMPERATURE BAKE AT 150 DEG C</b>					
<b>PACKAGE TYPE</b>	<b>SAMPLE SIZE</b>	<b>OLDEST DATE CODE</b>	<b>NEWEST DATE CODE</b>	<b>K DEVICE HRS</b>	<b>No. of FAILURES</b>
QFN/DFN	3930	0739	1740	3651	0
SOIC/MSOP	1370	0739	1522	1370	0
SOT	308	0811	0811	154	0
Totals	5,608	-	-	5,175	0
<b>HIGH TEMPERATURE BAKE AT 175 DEG C</b>					
<b>PACKAGE TYPE</b>	<b>SAMPLE SIZE</b>	<b>OLDEST DATE CODE</b>	<b>NEWEST DATE CODE</b>	<b>K DEVICE HRS</b>	<b>No. of FAILURES</b>
DD PAK	1876	1223	1615	1876	0
QFN/DFN	3006	0552	1741	4783	0
SSOP/TSSOP	708	1227	1649	710	0
SOIC/MSOP	1370	0739	1703	1220	0
TO-220	1106	1247	1615	1106	0
SOT	1680	0836	1648	1617	0
Totals	9,746	-	-	11,312	0